



Features and Benefits

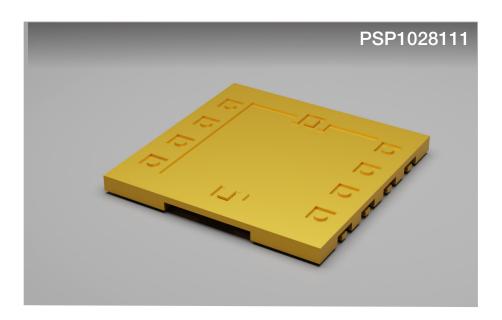
• Ultra Low Loss, less than 0.3 dB insertion loss from DC to 50 GHz

- Ideal thermal performance due to solid copper construction
- Chip interface compatible with automated Au wire bonding

• PCB interface compatible with standard SMT processes

Applications

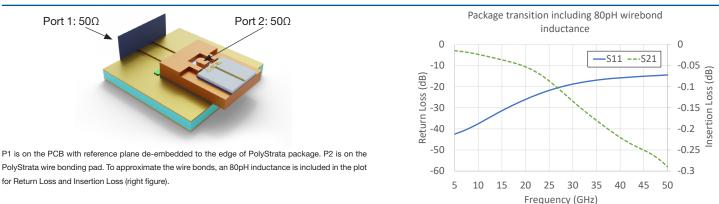
- Military
- Space
- Communications
- Instrumentation



PolyStrata[®] Package: PSP1028111

Market-leading lowest loss, surface mount form factor package for die under 3 x 3mm up to 50 GHz.

Cubic Nuvotronics presents a new state of the art Low Loss MMIC package. The PolyStrata® package complements integrated MMIC performance, with less than 0.3 dB insertion loss up to 50 GHz and with 15 dB typical return loss. The package can be surface mounted to a PCB using standard SMT processes. This increases the ease of manufacturing while maintaining superior performance in a smaller size compared to other packaging substrates.



Typical Electrical Performance



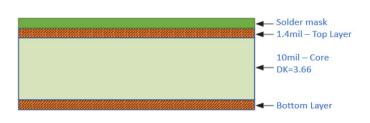
Additional Details

Special Handling / Storage Instructions (Substrate Only)		
Storage	Per JEP160 - Oxygen Sensitive Devices	
ESD Sensitivity	None	
Moisture Sensitivity	Not Applicable	
Component Termination Finish	Immersion Gold over Immersion Silver	
Packaging Available	Gel-Pak [®] , Tape and Reel	
Ordering Part Number	PSP1028111	
Export Classification	EAR99	
Lid Options	Compatible with metal or plastic lids, and most lid-sealing processes	

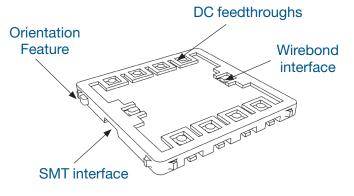
Absolute Maximum Ratings

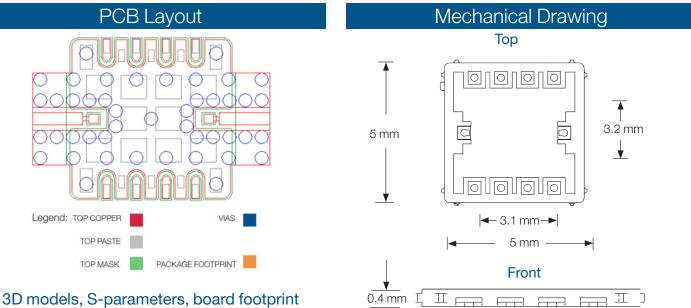
Current	2.0 amps
Operating Temp	-55°C to 125°C
Solder Reflow	Compatible with JEDEC J-STD-020
Epoxy Attach	150°C max. for 90 minutes

PCB Stack-up View



Component View





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